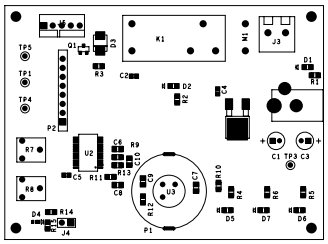
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
**	ORIGINAL DESIGN	12/18/06	DFK



PRIMARY SIDE

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. NELCO 4000-11 OR IS420 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, 1/2 oz. COPPER FOIL EXTERNAL LAYERS AND 1 oz. COPPER FOIL FOR INTERNAL LAYERS.
   C. OVERALL METAL TO METAL THICKNESS .063 +/- 10%.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO ETCH DATE CODE AND LOGO ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER, PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON; ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTIONS

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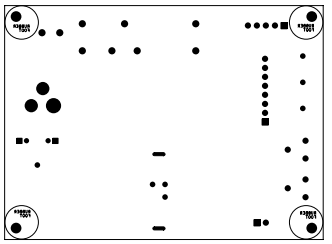
SIGNATURES		DATE
DRAWN	DFK	12/18/06
CHECKED	SNF	01/07/07
ENGRG	DFK	01/12/07
ISSUED		

CYPRESS SEMICONDUCTOR
10147 W EMERALD ST
BOISE, ID 83704

ASSEMBLY DRAWING
CY3236A-PIRMOTION

SIZE	FSCM NO	DWG NO	REV
C		PDCR-9377	**

SCALE: 1/1 SHEET: 1 OF 2



SECONDARY SIDE

CYPRESS SEMICONDUCTOR

10147 W EMERALD
BOISE, ID 83704

ASSEMBLY DRAWING
CY3236A-PIRMOTION

SIZE	FSCM NO	DWG NO	REV
C		PDCR-9377	**
SCALE: 1/1			SHEET: 2 OF 2